

EPJ AM

Applied Metamaterials

Call for papers

Themed Issue on *Global Advances in Electromagnetic Metasurfaces for Space*

Edited by

- Dr **Aakash Bansal**, *Royal Academy of Engg. UK IC Research Fellow and Lecturer in Applied Electromagnetics, Wolfson School of Mechanical, Electrical and Manufacturing Engineering, Loughborough University, UK*
- Dr. **Chinmoy Saha**, *Professor, Department of Avionics, Indian Institute of Space Science and Technology, India*
- Prof. **William Whittow**, *Professor of Radiofrequency Materials, Wolfson School of Mechanical, Electrical and Manufacturing Engineering, Loughborough University, UK*

Background

Metasurfaces are two- and three-dimensional periodic structures that can deliver unique features within all sorts of engineering domains. Within electromagnetics for space (be it radio frequency, microwave, millimeter-wave, terahertz, or optics), metasurfaces are popularly used

to manipulate electromagnetic waves using passive or active artificially created sub-wavelength patterned structures. Such innovative surfaces are being adapted in the literature for a number of RF and optical applications in space such as remote sensing, satellite communications, high-resolution imaging, beam-steering, and radar-cross section reduction.

Aim and Scope of the Themed Issue

This special issue aims to curate a collection highlighting the global advances in the development of electromagnetic metasurfaces for applications in space systems. It will focus on the exciting developments, ongoing trends and latest achievements in envisioning, simulating, fabricating, and measuring new metasurfaces for microwave, millimeter-wave, terahertz, and optical frequencies.

We invite submissions from all domains of applied and theoretical research on this subject which includes (but is not limited to):

- Fundamental theory and modeling of metasurfaces
- Active and tunable metasurfaces
- Reconfigurable intelligent surfaces
- Holographic metasurfaces
- Metasurface-based reflectors and lenses
- Metasurfaces for satellite communications networks
- Metasurfaces for remote sensing and imaging
- Metasurfaces for wavefront manipulation
- Metasurfaces for cloaking and invisibility
- Metasurfaces for optical and photonics applications
- Novel metasurface-based devices
- New emerging trends in metasurfaces

Submissions

All relevant papers will be carefully considered, vetted by a distinguished team of international experts, and published in accordance to the **Journal's standard policies**. Full research papers and comprehensive review articles can be submitted online via the journal's submission and peer review site.

Instructions for Authors at: <https://epjam.edp-open.org/author-information/instructions-for-authors>

Article Processing Charges

EPJ Applied Metamaterials is published in Open Access. An Article Processing Charge (APC) is applied. It covers the costs involved in the open access publication, such as editorial handling, copyediting, data management, proofs, administrative overheads and technologies in order to make your article findable, accessible, interoperable and reusable.

For accepted articles submitted in 2024, the APC is 500€ (paid after acceptance). The journal does not have any submission fee.

Other Waivers and Discounts

- EDP Sciences provides a waiver to authors based in countries included in [Group A of the Research4Life programme](#)
- EDP Sciences has signed an APC agreement with the NSLC (National Science Library CAS) the research library service system for the Chinese Academy of Sciences (CAS). Corresponding authors affiliated with [one of the eligible CAS institutes](#), can publish in open access at a 20 percent discounted APC price.
- EDP Sciences has signed with the Technische Informationsbibliothek (TIB) a German National APC agreement. Corresponding authors affiliated with German academic institutions including universities and research institutions, can publish in open access at a 20 percent discounted APC price.
- Corresponding authors from [French institutions](#) having signed [the National Open Access agreement in France](#), can publish in Open Access without any fee.

Submission deadline – February 1st 2025

Article submission and editorial system [here](#).

Abstracting/indexing

- | | |
|--|--|
| <ul style="list-style-type: none">• Astrophysics Data System (ADS)• Cabells Journalytics• DOAJ - Directory of Open Access Journals• Ebsco Discovery• EI Compendex• ESCI - Emerging Sources Citation Index (Web of Science)• IET INSPEC | <ul style="list-style-type: none">• Materials Science & Engineering Database (ProQuest)• Portico• SciTech Premium Collection (ProQuest)• Scopus• TIB Lizenzen Technische Informationsbibliothek (TIB)• Wanfang Data |
|--|--|

2023 Impact Factor*: 1.5

***Journal Citation Reports™ from Clarivate, 2024**

Editorial board

Editor in Chief

Yang Hao, Queen Mary, University of London

Associate Editors

Andrea Alu, CUNY Advanced Science Research Center, City College of New York, USA

Runhua Fan, Shanghai Maritime University and Chinese Metamaterials Society, China

Maria Kafesaki, University of Crete, Greece

Jensen Li, University of Birmingham

Editors

Tahsin Akalin, Institute of Electronic, Microelectronic and Nanotechnology (IEMN), DHS Dpt., Lille University, France, [website](#)

Christos Argyropoulos, University of Nebraska-Lincoln, USA, [website](#)

Pavel Belov, ITMO, Russia

Filiberto Bilotti, University of Roma Tre, Italy

Alexandra Boltasseva, Purdue University, USA

Tiejun Cui, Southeast University, China

Yijun Feng, Nanjing University, China

Vincent Ginis, Vrije Universiteit Brussel, Belgium, [website](#)

Anthony Grbic, University of Michigan, USA

Sebastien Guenneau, Imperial College London, UK

Sailing He, Zhejiang University, China

Alastair Hibbins, University of Exeter, UK

Mikhail Lapine, University of Sydney, Australia

Stefan Maier, Imperial College London, UK

Alessio Monti, Niccolò Cusano University, Italy, [website](#)

Cheng-Wei Qiu, National University of Singapore, Singapore

Carsten Rockstuhl, University of Jena, Germany

Stefano Vellucci, Niccolò Cusano University, Italy

Doug Werner, Penn State University, USA

Yongmin Liu, Northeastern University, US